

KY8030-3

World-Fastest True 3D Solder Paste Inspection



Real Time Warp Compensation Solution



User-friendly Software



3D Measurement based SMT Process Control System







KY8030-3

World-Fastest True 3D Solder Paste Inspection



High Speed for Maximum Throughput

Optional

✓ Achieving industry leading inspection

speed at 0.24sec/FOV

KY8030-3 delivers true 3D inspection without concern for inaccuracies resulting from shadowing.

Dual Projection Technology

Projection

light



Warp Compensation Solution



Camera

Projection

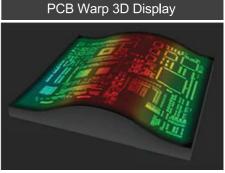
light

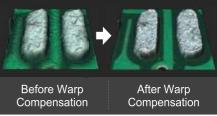
Z-tracking 3D Compensation Solution

- Koh Young's Multi-Frequency technology applied
- Real time measurement and compensation of board warp, with respect to the ideal plane
- Real time online provision of high quality PCB images with measurement data

Pad Referencing 2D Compensation Solution

- Automatic reference teaching by using high quality IR light
- Real time matching of the PCB ideal stencil design with the ideal PCB pad locations as defined by the CAD file

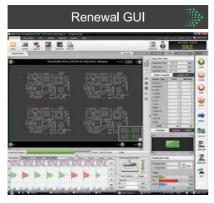


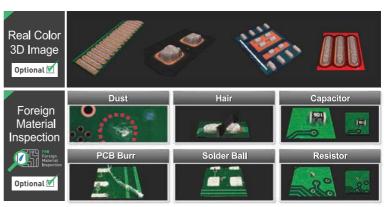




User-friendly Renewal GUI

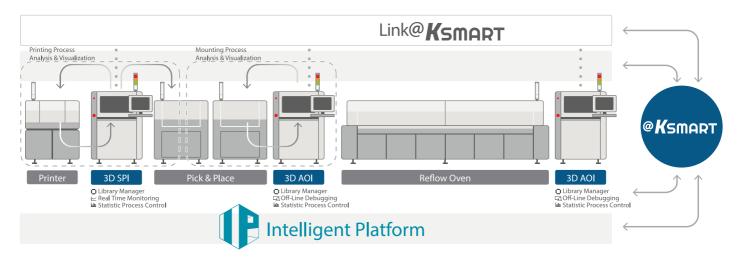
- Optimized display for the user with smart menu groupings
- Supports user's defect readability and system usability by more intuitive software
- Detects a wide range of defects using real images and 3D data







Intelligent Platform to Realize Fully Automated Process Optimization : Smart Factory

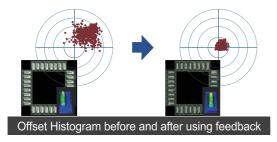




KSMART Process Optimizer

Optional 🗹

- Real time communication of printing process monitoring data with Screen Printers
- Supports pick-and-place process optimization by controlling panels containing defects



- Less Human Intervention
- · Live Feedback without Sarcrificing Cycle Time



- Printing Quality Improvement
- Yield Improvement



SPC @ KSMART



Reliable 3D Data based Statistical Process Control

- Carry out essential analyses from an intuitive graphical interface
- Accelerate root cause analysis for increased equipment uptime





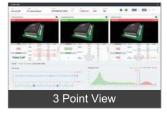
LINK (S) @ KSMART

Link@KSMART



3D data based SPI-AOI communication solution

- Review, diagnosis and optimization of printing, pick-and-place and reflow process
- Traces root cause of defects by storing and communicating inspection results from Koh Young's 3D SPI and 3D AOI Systems



Must-check Requirements of 3D SPI System



Requirem	ents	Solutions			
Solution to Shadow Problem		3D Shadow Free Moiré Technology & Dual Projection			
Real time PCB Warp Compensation (2D+3D Solution)		Warp Compensation (Pad Referencing + Z-tracking)			
Operator User-friendliness		Renewal GUI, Real Color 3D Image			
Inspection Range		Up to 2mm (4 Way Projection / optional)			
Foreign Material Inspection		3D Foreign Material Inspection (optional)			
Inspection	Metrology Capability	Volume, Area, Height, Offset, Bridging, Shape Deformity, Coplanarity			
Items	Types of Defects	Insufficient/Excessive/Missing Paste, Bridging, Shape Deformity, Paste Offset, Coplanarity			
	Camera Resolution	10μm 15μm 20μm			
	FOV Size	20×20mm(0.79×0.79 inch)	30×30mm(1.18×1.18 inch)	40×40mm(1.57×1.57 inch)	
	Full 3D Inspection Speed	13.7~43.5 cm²/sec (Inspection speed varies by PCB and inspection condition.)			
	with High Speed Option	16.2 ~ 50.8 cm²/sec (Inspection speed varies by PCB and inspection condition.)			
Inspection Performance	Min. Distance between Paste Deposit	100μm (3.94 mils) 150μm (5.91 mils) 200μm (7.87 mils)			
	Camera	4M Pixel Camera			
	Illumination	IR-RGB LED Dome Styled Illumination			
	Z Resolution	• 0.37µm			
	Height Accuracy (on KY Calibration target)	• 1µm			
	01005mm Inspection Capacity Gage R&R (±50% tolerance)	< 10% at 6σ			
	Max. Inspection Size	• 10×10mm 0.39×0.39 inch			
	Max. Inspection Height	• 400µm 15.75 mils			
	Min. Distance between PADs	• 100 µm (based on 150 µm paste height) 3.94 mils (5.91 paste height)			
	Various colored PCB Inspection	• Possible			
PCB Handling	Conveyor Width Adjustment	Automatic			
	Conveyor Fix Type	Front / Rear Fixed (factory setting)			
	Supported Input Format	Gerber Data (274X, 274D), ODB++ (optional)			
	Programming S/W	• ePM-SPI			
Software	Statistical Process Control Tool	 SPC@KSMART Histogram, X-bar & R-Chart, X-bar & S-Chart, Cp & Cpk, %Gage R&R Real Time SPC & Multiple Display SPC Alarm Remote Monitoring System 			
	Operator User-friendliness	 Library Manager@KSMART KYCal: Auto Camera Calibration, Auto Illumination Calibration, Auto Height Calibration 			
	Operating System	Windows 7 Ultimate 64bit			
Add-on Solutions	 1D & 2D Handy Barcode Reader 1D & 2D Inline Barcode Reader Offline Programming Station Offline SPC Plus Station Standard Calibration Target UPS 	 Remote Monitoring Sys Warp Compensation Foreign Material Inspect Review Station KSMART Process Option 	etion •	4 Way Projection Panasonic APC Link@KSMART SPC@KSMART	

* Above specifications are subject to change without notice.

	M	L	DL	XL	
Max. PCB Size	330X330mm (13X13 inch)	510X510mm (20X20 inch)	Dual: 510X320mm (20X12.6 inch) Single: 510X580mm (20X22.8 inch)	850X690mm (33.4X27.1 inch)	
Min. PCB Size	Min. PCB Size 50X50mm (1.97X1.97 inch)				
PCB Thickness	0.4~5mm (0.015~0.20 inch)			0.5~8mm (0.02~0.31 inch)	
Max. PCB Weight	Weight Standard: 2kg, Heavy Weight Option: 5kg			10kg(22 lbs)	
Machine Weight	550kg (1212 lbs)	600kg (1322 lbs)	700kg (1543 lbs)	850kg(1874 lbs)	
Bottom Side Clearance					
Supplies	200~240VAC, 50/60Hz Single Phase, 5Kgf/cm²				
W	820mm (32.2 inch)	1000mm (39.3 inch)		1350mm (53.1 inch)	
D	1295mm (50.9 inch)	1295mm (50.9 inch)	1475mm (58.0 inch)	1475mm (58.0 inch)	
Н	1727mm(67.9 inch)				
F	985mm (38.7 inch)		1165mm (45.8 inch)		

